

Report for the Chinese Semiconductor Industry 2019

<https://marketpublishers.com/r/R13835739F0EN.html>

Date: May 2019

Pages: 328

Price: US\$ 5,000.00 (Single User License)

ID: R13835739F0EN

Abstracts

It takes 3-5 business days to dispatch the report after the purchase is made.

Semiconductors refer to materials with conductive properties that range between true conductors and non-conductors in strength. Semiconductor technology can roughly be categorized into three branches, namely Integrated Circuits/microelectronics technology for information processing, storage and conversion, semiconductor components related electronics technology for power processing and conversion and photovoltaic components and photovoltaic technology for photovoltaic conversion.

The Chinese semiconductor industry itself is mainly concentrated around the Yangtze River Delta, the Pearl River Delta and the Bohai Bay area. The industry as a whole is still underdeveloped compared to that of other countries and is mostly known for mass-producing low quality products for exports while high quality components are imported from other countries. The industry itself is developing at a fast rate however.

The IC market achieved a figure of XX billion CNY in sales in 2018, a figure that represent XX% of total semiconductor sales in 2018. The IC manufacturing industry achieved a total of XX billion CNY in 2018, a XX% growth over the previous year.

The Chinese semiconductor industry itself is currently in its earliest stages of development and thus heavily relies on imports for high quality products. This has also allowed for the Chinese market to become the largest importer of semiconductor products. The semiconductor market is expected to reach a scale of XX CNY by 2025.

Contents

CHAPTER 1 SEMICONDUCTOR INDUSTRY OVERVIEW

- 1.1 Semiconductor industry overview
 - 1.1.1 Semiconductor definition
 - 1.1.2 Semiconductor industry segments0
- 1.2 Semiconductor industry supply chain introduction
- 1.3 Semiconductor industry supply chain upstream analysis
 - 1.3.1 Semiconductor silicon
 - 1.3.1.1 Applications
 - 1.3.1.2 Production methods
 - 1.3.1.3 Supply analysis
 - 1.3.1.4 Development trends
 - 1.3.2 Gallium arsenide
 - 1.3.2.1 Applications
 - 1.3.2.2 Production methods
 - 1.3.2.3 Supply analysis
 - 1.3.2.4 Development trends
 - 1.3.3 Gallium nitride
 - 1.3.3.1 Applications
 - 1.3.3.2 Production methods
 - 1.3.3.3 Pricing analysis
 - 1.3.3.4 Prospects analysis
- 1.4 Semiconductor industry supply chain downstream analysis
 - 1.4.1 Computer industry
 - 1.4.2 Consumer electronics industry
 - 1.4.3 Communication devices industry
 - 1.4.4 Vehicle electronics industry
 - 1.4.5 Smart network industry
 - 1.4.6 Industry control market

CHAPTER 2 INTERNATIONAL SEMICONDUCTOR INDUSTRY DEVELOPMENT ANALYSIS

- 2.1 International semiconductor industry development trends
 - 2.1.1 International semiconductor market development
 - 2.1.2 International semiconductor market size
 - 2.1.2.1 International semiconductor industry size

- 2.1.2.2 International IC market size
- 2.1.2.3 Semiconductor component market size
- 2.1.2.4 Optoelectronics industry market size
- 2.1.3 Semiconductor industry profitability and changes
- 2.1.4 International semiconductor market structure
 - 2.1.4.1 International semiconductor market product application structure
 - 2.1.4.2 International semiconductor market regional structure
- 2.2 International semiconductor industry competitive analysis
 - 2.2.1 International semiconductor industry competitiveness
 - 2.2.2 IC market competitiveness
 - 2.2.3 semi-conductor market competitiveness
 - 2.2.4 Optoelectronics industry competitiveness
- 2.3 Leading global semiconductor firms in China
 - 2.3.1 Intel
 - 2.3.1.1 Development overview
 - 2.3.1.2 Main products
 - 2.3.1.3 Operational overview
 - 2.3.1.4 Investments in China
 - 2.3.2 Texas Instruments (TI)
 - 2.3.2.1 Development overview
 - 2.3.2.2 Main products
 - 2.3.2.3 Operational overview
 - 2.3.2.4 Investments in China
 - 2.3.3 Qualcomm
 - 2.3.3.1 Development overview
 - 2.3.3.2 Main products
 - 2.3.3.3 Operational overview
 - 2.3.3.4 Investments in china
 - 2.3.4 NXP Semiconductors
 - 2.3.4.1 Development overview
 - 2.3.4.2 Main products
 - 2.3.4.3 Operational overview
 - 2.3.4.4 Investments in China
 - 2.3.5 AMD
 - 2.3.5.1 Development overview
 - 2.3.5.2 Main products
 - 2.3.5.3 Operational overview
 - 2.3.5.4 Investments in China
 - 2.3.6 ADI

2.3.6.1 Development overview

2.3.6.2 Main products

2.3.6.3 Operational overview

2.3.6.4 Investments in China

2.3.7 NEC

2.3.7.1 Development overview

2.3.7.2 Main products

2.3.7.3 Operational overview

2.3.7.4 Investments in China

2.3.8 Toshiba

2.3.8.1 Development overview

2.3.8.2 Main products

2.3.8.3 Operational overview

2.3.8.4 Investments in China

2.3.9 ST

2.3.9.1 Development overview

2.3.9.2 Main products

2.3.9.3 Operational overview

2.3.9.4 Investments in China

2.3.10 Samsung

2.3.10.1 Development overview

2.3.10.2 Main products

2.3.10.3 Operational overview

2.3.10.4 Investments in China

CHAPTER 3 CHINESE SEMICONDUCTOR INDUSTRY DEVELOPMENTS

3.1 Chinese semiconductor industry development policies

3.1.1 Semiconductor industry regulatory bodies

3.1.1.1 Governing bodies

3.1.1.2 Self-regulatory organizations

3.1.2 Semiconductor industry policies

3.2 Chinese semiconductor industry development analysis

3.2.1 Chinese semiconductor industry development history

3.2.2 Semiconductor industry market size analysis

3.2.2.1 Semiconductor market size

3.2.2.2 IC market size

3.2.2.3 Components market size

3.3 Semiconductor industry business models analysis

- 3.3.1 Main business models
 - 3.3.1.1 IDM business model analysis
 - 3.3.1.2 Vertical business model
- 3.3.2 Competition and cooperation between business models
- 3.3.3 Entry barriers and profits for business models
- 3.4 Semiconductor industry market competition analysis
 - 3.4.1 Semiconductor industry company competitiveness
 - 3.4.1.1 Semiconductor industry competitiveness
 - 3.4.1.2 IC industry competitiveness
 - 3.4.1.3 Components industry competitiveness
 - 3.4.2 Semiconductor industry SWOT analysis
 - 3.4.2.1 Strengths
 - 3.4.2.2 Weaknesses
 - 3.4.2.3 Opportunities
 - 3.4.2.4 Threats
- 3.5 Competitive strategies for domestic companies

CHAPTER 4 CHINESE SEMICONDUCTOR INDUSTRY SEGMENT DEVELOPMENT STRATEGIES

- 4.1 IC industry developments
 - 4.1.1 Development overview
 - 4.1.1.1 Product types and categories
 - 4.1.1.2 Industry chain analysis
 - 4.1.1.3 Industry structure analysis
 - 4.1.1.4 Industry developments
 - 4.1.2 IC design industry developments
 - 4.1.2.1 Development overview
 - 4.1.2.2 Industry characteristics
 - 4.1.2.3 Operational models
 - 4.1.2.4 Development scale
 - 4.1.2.5 Industry competitiveness
 - 4.1.3 IC manufacturing industry analysis
 - 4.1.3.1 Development overview
 - 4.1.3.2 Development bottlenecks
 - 4.1.3.3 Development scale
 - 4.1.3.4 Industry competitiveness
 - 4.1.4 IC measuring industry development analysis
 - 4.1.4.1 Development overview

- 4.1.4.2 Operational models
- 4.1.4.3 Development scale
- 4.1.4.4 Industry competitiveness
- 4.1.4.5 Industry segments
- 4.1.5 IC industry production scale
- 4.1.6 IC production distribution
- 4.1.7 IC industry economic data
 - 4.1.7.1 Number of companies
 - 4.1.7.2 Industry finances
 - 4.1.7.3 Sales income
 - 4.1.7.4 Total profits
- 4.1.8 IC industry operational efficiency
 - 4.1.8.1 Industry profitability
 - 4.1.8.2 Profit margins
 - 4.1.8.3 Operational capability
 - 4.1.8.4 Debt repayment capability
- 4.2 Semiconductor components industry analysis
 - 4.2.1 Semiconductor components general analysis
 - 4.2.1.1 Product structure
 - 4.2.1.2 Industry chain analysis
 - 4.2.2 Component industry development overview
 - 4.2.3 Production growth analysis
 - 4.2.4 Manufacturing distribution
 - 4.2.5 Economic operations
 - 4.2.5.1 Component industry companies
 - 4.2.5.2 Income scale
 - 4.2.5.3 Sales income
 - 4.2.5.4 Profits
 - 4.2.6 Semiconductor components industry operational efficiency analysis
 - 4.2.6.1 Profitability
 - 4.2.6.2 Profit margins
 - 4.2.6.3 Operational capability
 - 4.2.6.4 Debt repayment capability
- 4.3 Optoelectronics industry development analysis
 - 4.3.1 Development overview
 - 4.3.1.1 Supply chain analysis
 - 4.3.1.2 Product structure
 - 4.3.2 Production growth rates
 - 4.3.3 Production distribution

- 4.3.4 Development of semiconductor optoelectronics components
 - 4.3.4.1 LDs
 - 4.3.4.2 Light sensitive camera components
 - 4.3.4.3 Surface optoelectronics components
- 4.3.5 Optoelectronics industry investments analysis

CHAPTER 5 SEMICONDUCTOR INDUSTRY APPLICATION MARKETS ANALYSIS

- 5.1 Computer industry semiconductor market analysis
 - 5.1.1 Computer industry development overview
 - 5.1.2 Main product production figures
 - 5.1.3 Demand characteristics
 - 5.1.4 Demand scale
- 5.2 Consumer electronics semiconductor market analysis
 - 5.2.1 Consumer electronics industry development overview
 - 5.2.2 Main product production figures
 - 5.2.3 Demand characteristics
 - 5.2.4 Competitiveness
 - 5.2.5 Demand scale
- 5.3 Automobile electronics industry semiconductor market analysis
 - 5.3.1 Automobile electronics industry development overview
 - 5.3.2 Main product production figures
 - 5.3.3 Semiconductor demands
 - 5.3.4 Automobile electronics semiconductor vendors
- 5.4 Industry control semiconductor market analysis
 - 5.4.1 Development overview
 - 5.4.2 Main product production figures
 - 5.4.3 Semiconductor demand characteristics
 - 5.4.4 Vendors
- 5.5 Communication devices semiconductor market analysis
 - 5.5.1 Development overview
 - 5.5.2 Main product production figures
 - 5.5.3 Demand characteristics
 - 5.5.4 Applications
 - 5.5.5 Demand scale
- 5.6 Smart grid semiconductor market analysis
 - 5.6.1 Development overview
 - 5.6.2 Demand analysis
 - 5.6.3 Vendors

- 5.6.4 Demand prospects
- 5.7 Photovoltaic industry semiconductor market analysis
 - 5.7.1 Development overview
 - 5.7.2 Demand analysis
 - 5.7.3 Demand characteristics
 - 5.7.4 Demand prospects
- 5.8 LED lighting sector semiconductor market analysis
 - 5.8.1 LED lighting industry development overview
 - 5.8.2 Demand analysis
 - 5.8.3 Pricing trends
 - 5.8.4 Demand prospects

CHAPTER 6 IMPORTS AND EXPORTS ANALYSIS

- 6.1 Processor and controller units 2011-2016
 - 6.1.1 Imports
 - 6.1.1.1 Import figures
 - 6.1.1.2 Import finances
 - 6.1.1.3 Import sources
 - 6.1.1.4 Average pricing
 - 6.1.2 Exports
 - 6.1.2.1 Export figures
 - 6.1.2.2 Export finances
 - 6.1.2.3 Export recipients
 - 6.1.2.4 Average pricing
- 6.2 Semiconductor memory
 - 6.2.1 Imports and exports
 - 6.2.1.1 Import figures
 - 6.2.1.2 Import finances
 - 6.2.1.3 Import sources
 - 6.2.1.4 Average pricing
 - 6.2.2 Exports
 - 6.2.2.1 Export figures
 - 6.2.2.2 Export finances
 - 6.2.2.3 Export recipients
 - 6.2.2.4 Export average pricing
- 6.3 Imports and exports analyses for transistors with power dissipation rates lower 1 watt
 - 6.3.1 Sub-1-watt transistors import analysis

- 6.3.1.1 Import figures
- 6.3.1.2 Import finances
- 6.3.1.3 Import sources
- 6.3.1.4 Import average prices
- 6.3.2 Exports
 - 6.3.2.1 Export figures
 - 6.3.2.2 Export finances
 - 6.3.2.3 Recipients
 - 6.3.2.4 Export average prices
- 6.4 Import and Export analyses for transistors with power dissipation rates higher than 1 watt 2011-2016
 - 6.4.1 Import analysis
 - 6.4.1.1 Import figures
 - 6.4.1.2 Import finances
 - 6.4.1.3 Import sources
 - 6.4.1.4 Import average prices
 - 6.4.2 Export analysis
 - 6.4.2.1 Export figures
 - 6.4.2.2 Export finances
 - 6.4.2.3 Recipients
 - 6.4.2.4 Export average prices
- 6.5 Diodes import and export analyses 2011-2016
 - 6.5.1 Import analysis
 - 6.5.1.1 Import figures
 - 6.5.1.2 Import finances
 - 6.5.1.3 Import sources
 - 6.5.1.4 Import average pricing
 - 6.5.2 Export analysis
 - 6.5.2.1 Export figures
 - 6.5.2.2 Export finances
 - 6.5.2.3 Recipients
 - 6.5.2.4 Export average pricing
- 6.6 LED import and export analyses 2011-2016
 - 6.6.1 LED import analysis
 - 6.6.1.1 Import figures
 - 6.6.1.2 Import finances
 - 6.6.1.3 Import sources
 - 6.6.1.4 Import average pricing
 - 6.6.2 LED export analysis

- 6.6.2.1 Export figures
- 6.6.2.2 Export finances
- 6.6.2.3 Recipients
- 6.6.2.4 Export average pricing

CHAPTER 7 CHINESE REGIONAL SEMICONDUCTOR INDUSTRY MARKETS COMPETITIVENESS ANALYSIS

7.1 Yangtze Delta

7.1.1 Shanghai

- 7.1.1.1 Development environment
- 7.1.1.2 Industry distribution
- 7.1.1.3 Production figures
- 7.1.1.4 Demand prospects
- 7.1.1.5 Development overview

7.1.2 Jiangsu

- 7.1.2.1 Development environment
- 7.1.2.2 Industry distribution
- 7.1.2.3 Production figures
- 7.1.2.4 Demand prospects
- 7.1.2.5 Development overview

7.1.3 Zhejiang Province

- 7.1.3.1 Development environment
- 7.1.3.2 Industry distribution
- 7.1.3.3 Production figures
- 7.1.3.4 Demand prospects
- 7.1.3.5 Development overview

7.2 Pearl river delta semiconductor industry competitiveness analysis

7.2.1 Guangzhou

- 7.2.1.1 Development environment
- 7.2.1.2 Industry distribution
- 7.2.1.3 Photovoltaic development prospects
- 7.2.1.4 Demand prospects

7.2.2 Shenzhen

- 7.2.2.1 Development environment
- 7.2.2.2 Industry distribution
- 7.2.2.3 Competitive advantages
- 7.2.2.4 Demand prospects

7.2.3 Dongguan

- 7.2.3.1 Development environment
- 7.2.3.2 Industry distribution
- 7.2.3.3 Competitive advantages
- 7.2.3.4 Demand prospects
- 7.3 Bohai bay area semiconductor industry competitiveness analysis
 - 7.3.1 Beijing
 - 7.3.1.1 Development environment
 - 7.3.1.2 Industry distribution
 - 7.3.1.3 Main products production figures
 - 7.3.1.4 Demand prospects
 - 7.3.1.5 Market developments
 - 7.3.2 Tianjin
 - 7.3.2.1 Development environment
 - 7.3.2.2 Industry distribution
 - 7.3.2.3 Main product production
 - 7.3.2.4 Demand prospects

CHAPTER 8 CHINESE SEMICONDUCTOR INDUSTRY TRANSFORMATIVE STRATEGIES

- 8.1 Industry base strategies
 - 8.1.1 Yangtze Delta
 - 8.1.2 Pearl River Delta
 - 8.1.3 Bohai Bay
- 8.2 Semiconductor companies' transformative strategies
 - 8.2.1 Main modes
 - 8.2.2 Extensions
 - 8.2.3 M&A
 - 8.2.4 International expansion
- 8.3 Main methods of implementation
 - 8.3.1 Brand creation
 - 8.3.2 Transitioning from manufacturing to services
 - 8.3.4 From low to high quality
 - 8.3.5 Supply chain resource integration
- 8.4 Semiconductor companies' transformative strategies analysis
 - 8.4.1 Differentiation
 - 8.4.2 Quality
 - 8.4.3 Sustainable development
 - 8.4.4 Beneficial cooperation

8.4.5 International operations

CHAPTER 9 LEADING COMPANIES

9.1 Ingenic

9.1.1 Overview

9.1.2 Products

9.1.3 Operational overview

9.1.4 Development strategies

9.2 Xiaocheng Technologies

9.2.1 Overview

9.2.2 Products

9.2.3 Operational overview

9.2.4 Development strategies

9.3 China Electronics

9.3.1 Overview

9.3.2 Products

9.3.3 Operational overview

9.3.4 Competitive advantages

9.4 Fujitsu-NT

9.4.1 Overview

9.4.2 Products

9.4.3 Operational overview

9.4.4 Competitive advantages

9.5 Huatian Technologies

9.5.1 Overview

9.5.2 Products

9.5.3 Operational overview

9.5.4 Competitive advantages

9.6 Silan Electronics

9.6.1 Overview

9.6.2 Products

9.6.3 Operational overview

9.6.4 Competitive advantages

9.7 Sinowealth

9.7.1 Overview

9.7.2 Products

9.7.3 Operational overview

9.7.4 Development strategies

9.8 Goodark Electronics Holdings

9.8.1 Overview

9.8.2 Products

9.8.3 Operational overview

9.8.4 Competitive advantages

9.9 Sinomicroelectronics

9.9.1 Overview

9.9.2 Products

9.9.3 Operational overview

9.9.4 Development strategies

9.10 Changjiang Electronics Technologies

9.10.1 Overview

9.10.2 Products

9.10.3 Operational overview

9.10.4 Competitive advantages

9.11 Shanghai Beiling

9.11.1 Overview

9.11.2 Products

9.11.3 Operational overview

9.11.4 Competitive advantages

9.12 Hcsemitek

9.12.1 Overview

9.12.2 Products

9.12.3 Operational overview

9.12.4 Development strategies

9.13 Nata Photovoltaic Materials

9.13.1 Overview

9.13.2 Products

9.13.3 Operational overview

9.13.4 Competitive advantages

9.14 Jinfu New Materials Holdings

9.14.1 Overview

9.14.2 Products

9.14.3 Operational overview

9.14.4 Competitive advantages

9.15 Hodgen Holdings

9.15.1 Overview

9.15.2 Products

9.15.3 Operational overview

- 9.15.4 Competitive advantages
- 9.16 Luxshare Precision Industries
 - 9.16.1 Overview
 - 9.16.2 Products
 - 9.16.3 Operational overview
 - 9.16.4 Competitive advantages
- 9.17 Techsem
 - 9.17.1 Overview
 - 9.17.2 Products
 - 9.17.3 Operational overview
 - 9.17.4 Competitive advantages
- 9.18 Microtek
 - 9.18.1 Overview
 - 9.18.2 Products
 - 9.18.3 Operational overview
 - 9.18.4 Competitive advantages

CHAPTER 10 TRANSFORMATIVE STRATEGY AND PROSPECTS ANALYSES FOR THE CHINESE SEMICONDUCTOR INDUSTRY 2019-2023

- 10.1 Chinese semiconductor industry development prospects 2019-2023
 - 10.1.1 Development drivers
 - 10.1.2 Prospects analysis
 - 10.1.3 Industry segment development analysis
 - 10.1.3.1 IC industry development trends
 - 10.1.3.2 Component industry development trends
 - 10.1.3.3 Photovoltaic instruments industry development trends
- 10.2 Industry development trends 2019-2023
 - 10.2.1 General development trends
 - 10.2.2 Industry segment development analysis
 - 10.2.2.1 IC industry development trends
 - 10.2.2.2 Component industry development trends
 - 10.2.2.3 Photovoltaic instruments industry development trends
- 10.3 2019-2023 Semiconductor industry projections
 - 10.3.1 Semiconductor industry market projections
 - 10.3.2 IC market projections
 - 10.3.3 Components market projections

CHAPTER 11 INVESTMENT RISKS AND STRATEGIES

- 11.1 2019-2023 Semiconductor industry investment environment
 - 11.1.1 Macroeconomic environment
 - 11.1.2 Photovoltaic development
 - 11.1.3 LED technology development
- 11.2 2019-2023 Investment opportunities and risks
 - 11.2.1 Semiconductor manufacturers characteristics
 - 11.2.2 Semiconductor industry investment opportunities
 - 11.2.2.1 IC industry
 - 11.2.2.2 Semiconductor components
 - 11.2.2.3 Photovoltaic equipment
 - 11.2.3 Investment risks
 - 11.2.3.1 Macroeconomic
 - 11.2.3.2 Competitive
 - 11.2.3.3 Product development
 - 11.2.3.4 Technical personnel
- 11.3 2019-2023 Semiconductor industry financing strategies and methods
 - 11.3.1 Methods and channels
 - 11.3.2 Equity financing
 - 11.3.3 Government channels
 - 11.3.4 Debt financing
 - 11.3.5 Following private and foreign investments

CHAPTER 12 CHINESE SEMICONDUCTOR COMPANIES FINANCING AND IPO STRATEGIES

- 12.1 Domestic IPO conditions and goals
 - 12.1.1 Goals
 - 12.1.2 Conditions
 - 12.1.2.1 Main board IPO conditions
 - 12.1.2.2 SME board conditions
 - 12.1.2.3 Secondary board conditions
 - 12.1.3 Core aspects of IPO
- 12.2 Preparations
 - 12.2.1 Necessity
 - 12.2.2 Timing
 - 12.2.3 Location
 - 12.2.4 Pre-IPO preparations
 - 12.2.4.1 Pre-listing assessment

- 12.2.4.2 Internal reorganization
- 12.2.4.3 Selection of intermediary organizations
- 12.2.4.4 Selection criteria
- 12.3 IPO planning and implementation
 - 12.3.1 IPO budgeting and team shuffling
 - 12.3.2 Due diligence and solutions
 - 12.3.3 Team shuffling precautions
 - 12.3.4 Public listing precautions and advice
 - 12.3.5 Necessary materials and requirements
 - 12.3.6 Online roadshows and prices
- 12.4 IPO processes
 - 12.4.1 Basic processes
 - 12.4.2 Other processes
 - 12.4.3 Related

I would like to order

Product name: Report for the Chinese Semiconductor Industry 2019

Product link: <https://marketpublishers.com/r/R13835739F0EN.html>

Price: US\$ 5,000.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/R13835739F0EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970